

Applications



Artificial Intelligence



Data/Computing



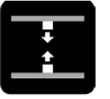
Telecommunications/Networking



High-Speed



Low Profile



Stacking

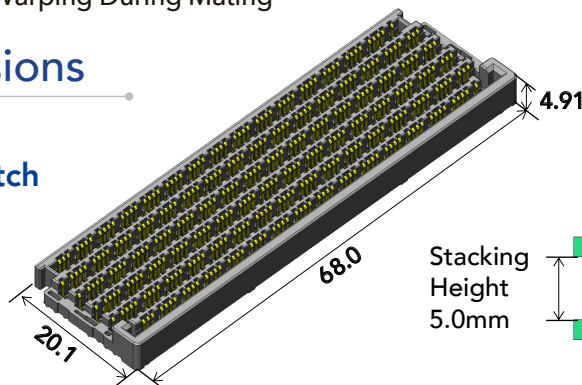
Low Stack Height High Speed (112Gbps PAM4) BGA Mezzanine Connector

0.9mm Pitch / 5mm Stacking Height

- Molex "Mirror Mezz" Licensed Second Source
- High Speed Transmission (56+Gbps NRZ / 112+Gbps PAM4)
- OAM Specified Connector
- High Pin Count, High Density : 688pos. (172DPs/in2)
- Hermaphroditic Connector
- Stub-less 2-point Contact Design
- Protective Housing that Encapsulates the Contact Tips Prevents Warping During Mating

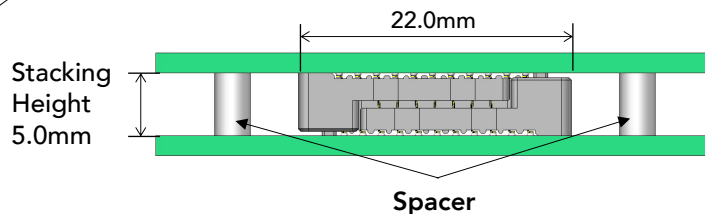
Dimensions

688pos.:
0.9mm Pitch



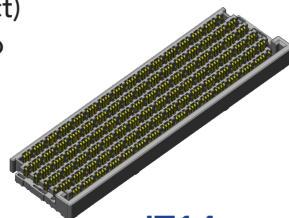
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Sample Number:
US-IT14SAMPLE-22

Mated Dimensions



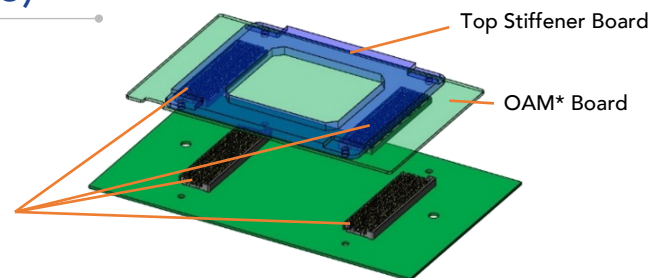
Used in OAM (OCP Accelerator Module)

The OCP (Open Compute Project) is a community of engineers who design and deliver the most efficient server, storage and data center hardware for scalable computing.



IT14:

5mm Stacking Height (2.5mm + 2.5mm)
688pos.
172 Differential Pairs



*OAM OCP Accelerator Module

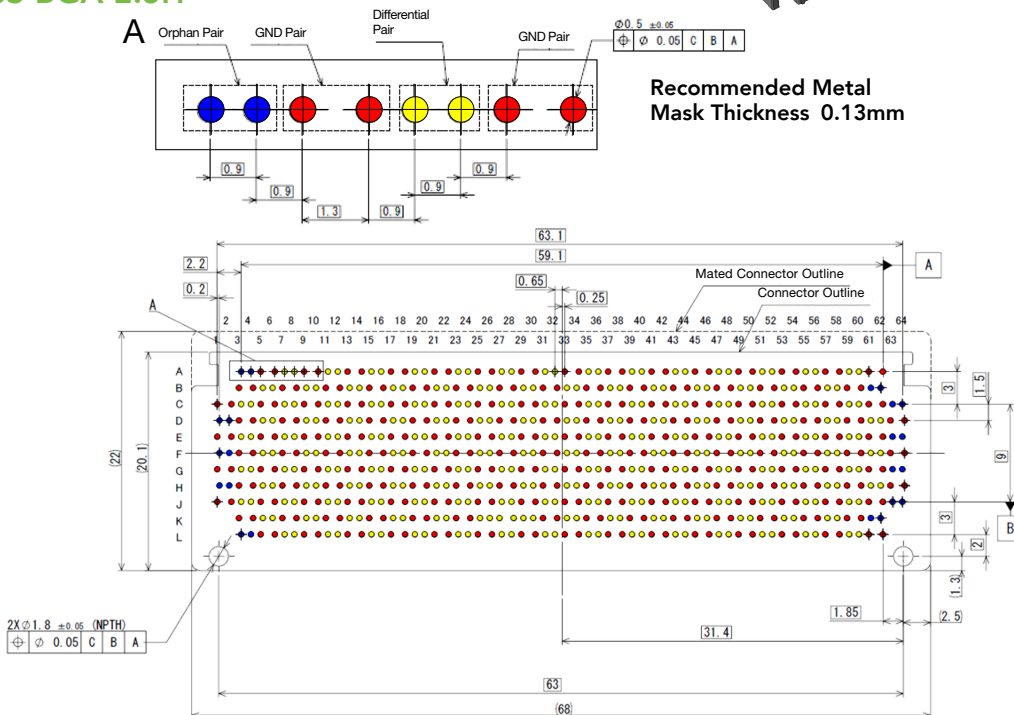
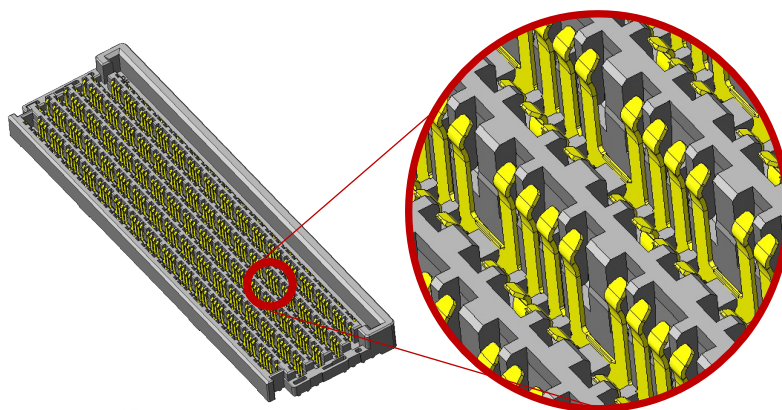
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FOR MORE INFORMATION

Contact Protection Design

Protective Housing Encapsulates the Contact Tips and Prevents Warping During Mating

Recommended PCB Mounting Pattern

IT14-688S-BGA-2.5H



Specifications

MATERIAL AND FINISH		
Component	Material	Finish/Remarks
Housing	LCP	UL94V-0/Black
Contact	Copper Alloy	Contact Area: Nickel + Gold Plating Other : Nickel
Solder Ball	Sn(96.5)-Ag(3)-Cu(0.5)	-

PERFORMANCE CHARACTERISTICS	
Rated Current	1.2A
Rated Voltage	30V AC/DC
Operating Temperature	-55 to +105°C
Contact Resistance*	30mΩ Max.
Withstanding Voltage	500V DC for 1 min.
Insulation Resistance	1000MΩ (500V DC)
Mating Durability	100 times